

2.4&5GHz 1608 Diplexer: LDP1608R2455L209

Applications:

WLAN, 802.11b/g, ISM Band...

Features

SMD, high reliability, ultra-Impact...

Part number

LDP 1608 R 2455 L2 09
(1) (2) (3) (4) (5) (6)

(1) Product code	LTCC-DPX
(2) Size code	1.6x0.8mm
(3) Packing	Tape and reel
(4) Frequency	2.4&5GHz
(5) Series	L2
(6) Type	09

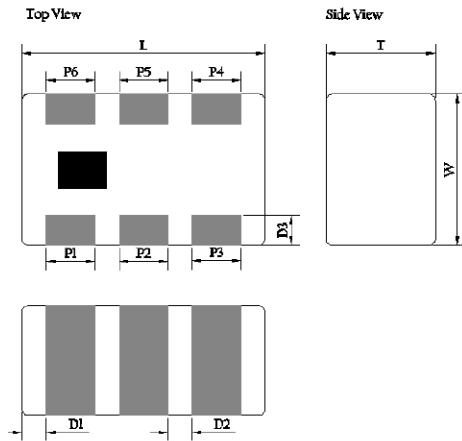
Electrical Specification

DESCRIPTION	VALUE	
Pass Band	LOW Band	High Band
	2400~2500MHz	4900~6000MHz
Insertion Loss	0.95dB (Max) at 25°C	0.90dB (Max) at 25°C
Return Loss	10.0dB(Min)	10.0dB(Min)
Attenuation	25dB(Min).@700~960MHz	30dB(Min).@1200~1500MHz
	10dB(Min).@960~1300MHz	25dB(Min).@1600~2000MHz
	28dB(Min).@4800~5000MH	25dB(Min).@2300~2700MHz
	z	15dB(Min).@2700~3000MHz
	25dB(Min).@7200~7500MH	25dB(Min).@10000~11800MHz
	z	15dB(Min).@15000~17700MHz
Isolation	28dB(Min).@2400~2500MHz	
	28dB(Min).@4800~5000MHz	
Operating Temperature	-40 ~ +85 °C	

The specification is defined on EVB.

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Dimension and Terminal Configuration

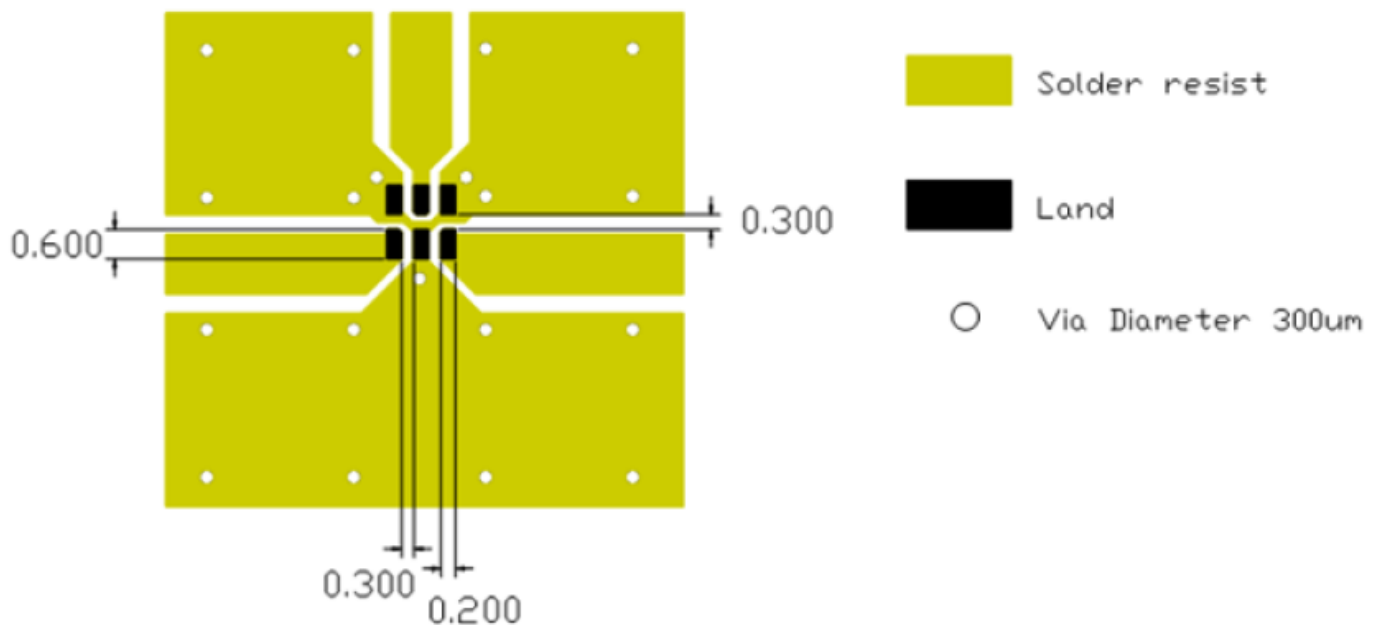


Dimension (mm)	
L (mm)	1.60 ± 0.15
W (mm)	0.80 ± 0.15
T (mm)	0.60 ± 0.15
P1 (mm)	0.20 ± 0.15
P2 (mm)	0.20 ± 0.15
P3 (mm)	0.20 ± 0.15
P4 (mm)	0.20 ± 0.15
P5 (mm)	0.20 ± 0.15
P6 (mm)	0.20 ± 0.15
D1 (mm)	0.20 ± 0.15
D2 (mm)	0.30 ± 0.10
D3 (mm)	0.15 ± 0.10

No.	Terminal Name
P1	High band
P2	GND
P3	Low band
P4	GND
P5	Common
P6	GND

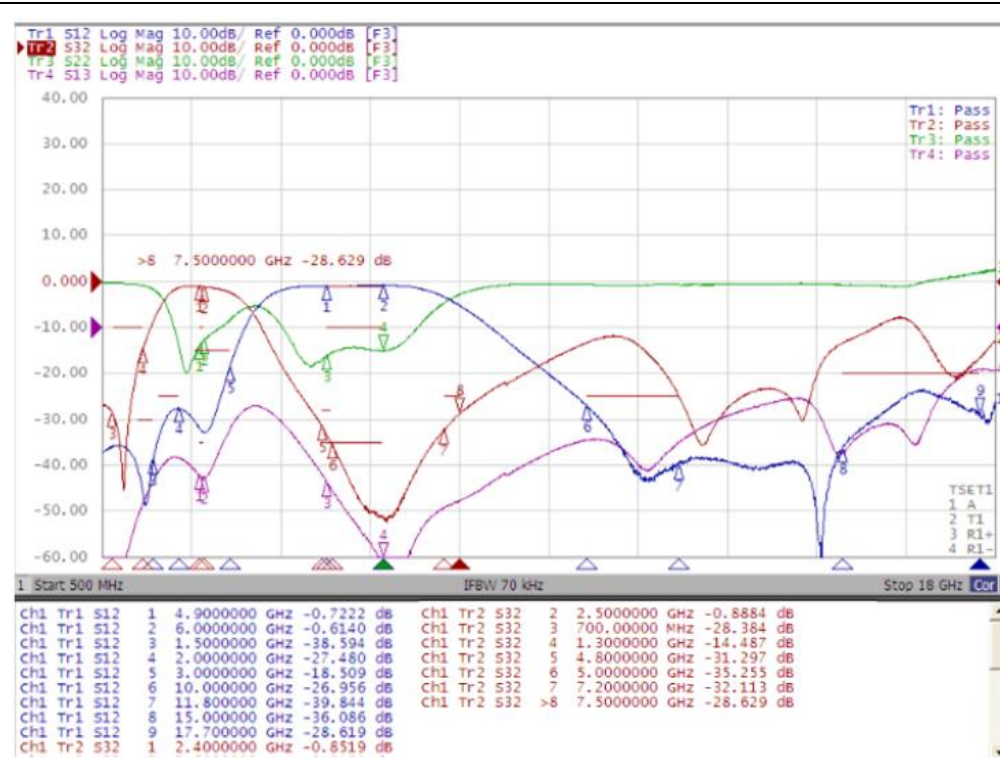
*P.S : Symmetrical,
No direction*

Evaluation Board Reference



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Electrical Characteristics



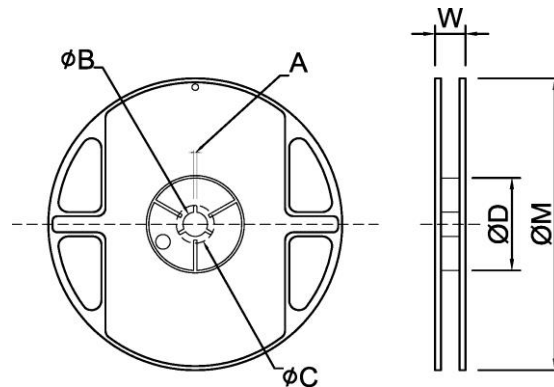
- Measured on Agilent E5071C Network Analyzer
- Common port : Port 2 (Return loss : S22)
- High band port : Port 1 (High band Insertion loss S12, and attenuation at high band)
- Low band port : Port 3 (Low band Insertion loss S32, and attenuation at low band)

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Taping Specifications

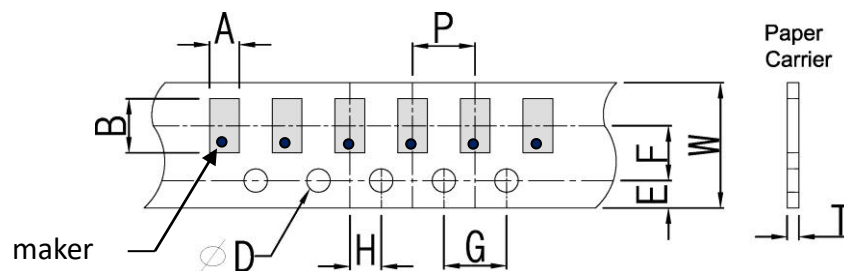
Reel and Taping Specification

Reel Specification



TYPE	SIZE		A	ϕB	ϕC	ϕD	W	ϕM
1608	7"	4K/Reel	2.0 ± 0.5	13.5 ± 1.0	21 ± 1.0	60 ± 1.0	11.5 ± 2.0	178 ± 2.0

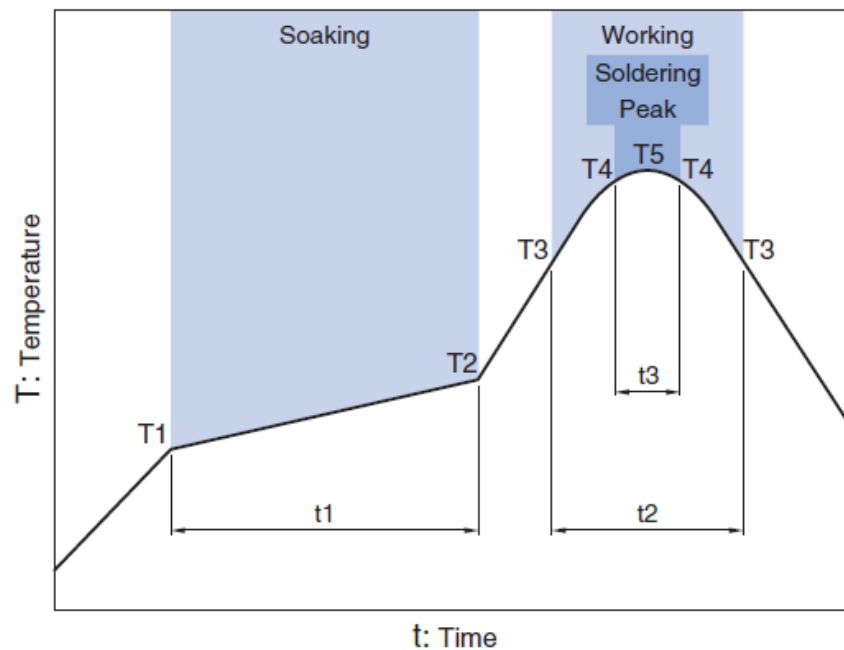
Taping Specification



Packaging	Type	A	B	W	E	F	G	H	T	ϕD	P
Paper Type	1608	1.40 ± 0.20	2.20 ± 0.20	8.0 ± 0.20	1.75 ± 0.10	3.0 ± 0.05	4.0 ± 0.10	2.0 ± 0.05	0.75 ± 0.10	$1.50^{+0.10}_{-0}$	4.0 ± 0.1

Recommended Reflow Profile

Pb free solder



Soaking			Working		Soldering		Peak
Temp.		Time	Temp.	Time	Temp.	Time	Temp.
T1	T2	t1	T3	t2	T4	t3	T5
150°C	180°C	60 to 120sec	230°C	more than 30sec	247 to 253°C	within 10sec	260°C Max.

Revision History

Version	Date	Description
Ver.01	Jul.2023	New issue.